

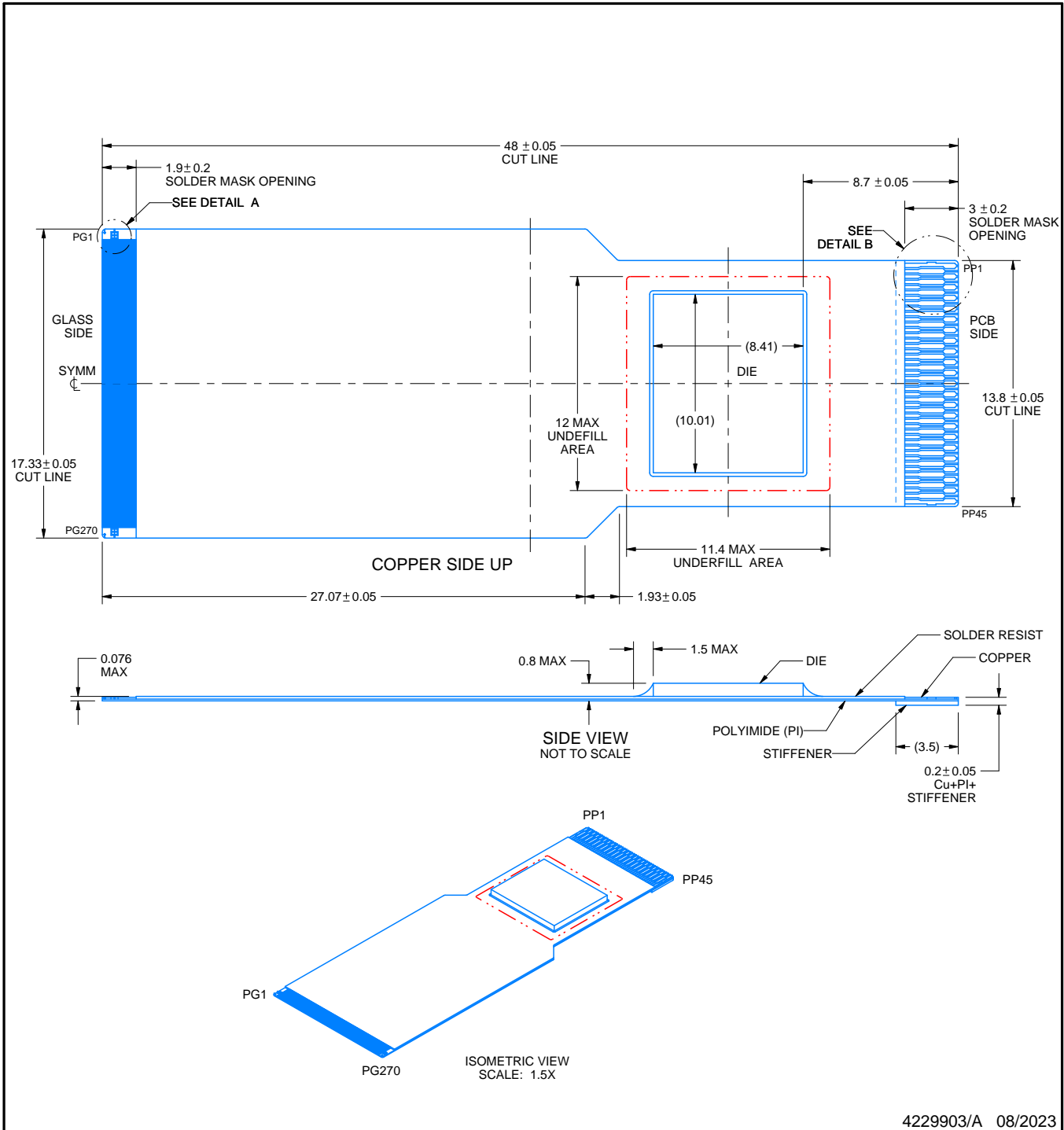
TFV0315A



PACKAGE OUTLINE

COF - 0.8 mm max height

CHIP ON FLEX



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NOTES:

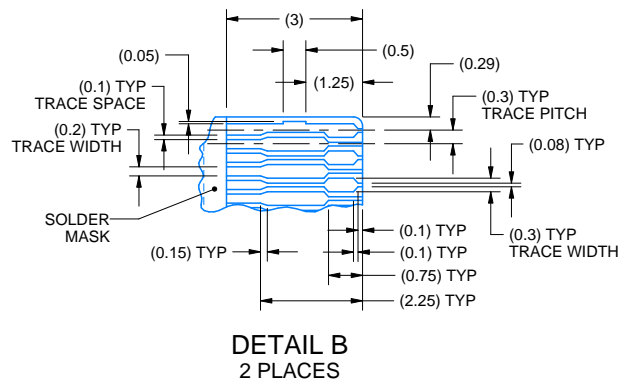
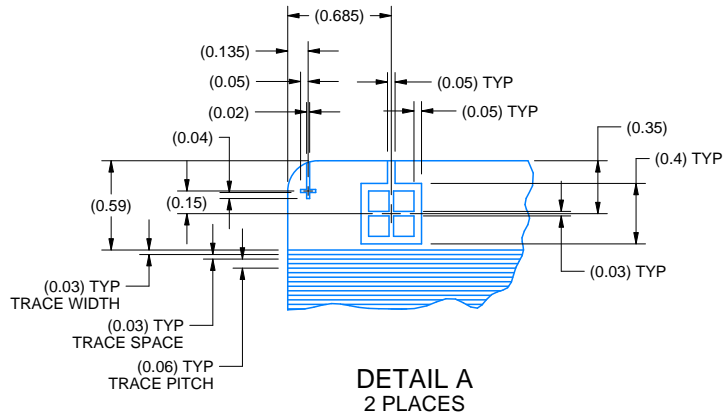
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. Flip chip application only.
4. The shrink factor of the COF on the glass side is 0.9987.

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